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(54) MODULE FOR OPTICAL COMMUNICATION AND INSPECTION METHOD THEREFOR

(57) Abstract:

PROBLEM TO BE SOLVED: To control the temperature of a semiconductor laser element from the outside of a package, to lower the price of a module for optical communication and to miniaturize it.

SOLUTION: A Peltier element 101 is provided on the bottom part of the package 100 and a base 102 is fixed on the Peltier element 101. On the base 102, the semiconductor laser element 103 and a photodetector 104 for monitoring are fixed. A recessed groove whose cross section is chevron-shaped is formed on the upper surface of the base 102 so as to be extended in an optical axis direction and the incident part 105a of an optical fiber 105 is fitted to the recessed groove. A fiber pressing member 106 provided with the recessed groove whose cross section is trapezoidal is fixed on the upper side of the base 102 and the incident part 105a of the optical fiber 105 is clamped by the base 102 and the fiber pressing member 106. A notched part 107 extended in a direction perpendicular to an optical axis is formed at the base 102 and the left end face of the optical fiber 105 is abutted on the wall surface on the side of the semiconductor laser element 103 of the notched part 107.

